**APPLICATION FOR GRADUATE ADMISSION**

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| --- | --- | --- | --- | --- | --- | --- |
| **Full Name(both English and Chinese)**  **\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_**  Family Given Middle Former(if any) | | | **PRC Citizen ID**  **/ Passport ID** | | | **photo** |
| **Gender:**   1. Male 2. Female | **Birthdate**  **\_\_\_\_\_-\_\_\_\_\_-\_\_\_\_\_**  Month Day Year | | **Birthplace**  **\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_**  City State Country | | |
| **Mailing Address (Chinese)**  Valid until\_\_\_\_\_\_\_\_\_\_  \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_  Daytime Phone: | | | **Email Address**  **Mobile Phone** | | | |
| **Citizenship:**   1. China 2. Other | | | |
| **Education** List all colleges and universities attended | | | | | | |
| University:  Department:  Major:  Date Attended:  Degree/Date Received:  GPA:  Comprehensive Ranking(Rank/total number compared):  综合排名: /  Academic Ranking(Rank/total number compared):  专业排名: / | | | University:  Department:  Major:  Date Attended:  Degree/Date Received :  GPA:  Comprehensive Ranking(Rank/total number compared):  综合排名: /  Academic Ranking(Rank/total number compared):  专业排名: / | | | |
| **Employer**  \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_  Company Name Location Position / Title From / To  \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_  Company Name Location Position / Title From / To | | | | | | |
| **Proposed Program( Master/PhD), Major and Direction 请填写你意向攻读的专业和方向** | | | | | | |
| □**PhD** □**Master** | | | | | | |
| **Majors** | | | | **Research Discipline Group** | | |
| □**Mechanics**  □**Mechanical Engineering**  □**Power Engineering and Engineering Thermophysics**  □**Electronic Science and Technology**  □**Information and Communication Engineering**  □**Control Science and Engineering**  □**Computer Science and Technology** | | | | □**Design, Manufacturing, and Systems**  □**Solid Mechanics**  □**Thermal Fluids**  □**Material Science & Engineering**  □**Circuits and Devices**  □**Electromagnetics, Optics, and Photonics**  □**Communications, Signal Processing, and Control**  □**Computer Science and Engineering** | | |
| **If you have taken any English test, please provide the name of test and your score** | | | | | | |
| **English Proficiency** | | | | | | |
| **CET6** Month/Year\_\_\_\_\_\_\_\_\_\_\_ Score\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ | | **TOEFL** Month/Year\_\_\_\_\_\_\_\_\_\_\_ Score\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ | | | **IELTS** Month/Year\_\_\_\_\_\_\_\_\_\_\_ Score\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ | |
| **Scholarships / Fellowships / Awards / Honors / Publications (Proof materials should be enclosed.)**  Scholarships and fellowships  Major academic recognitions, honors, and memberships  Significant professional activities and accomplishments  Significant extracurricular activities  Titles of publications, major papers, or theses authored or co-authored; if published, provide citation (Reprints included with the application cannot be returned.) | | | | | | |
| **Recommendations** Provide information of persons to whom you have submitted requests for recommendations.  Name Title Institution Department Email Telephone  Name Title Institution Department Email Telephone | | | | | | |
| **Certification and Signature**  I certify that I have answered all of the questions completely and truthfully. I understand that misrepresentation of any portion of this application, including supporting credentials and documents, may be cause for cancelling my admission, financial award, or appointment. I also understand that all credentials and documents that I submit become the property of Shanghai Jiao Tong University.  **\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_**  **Signature Date** | | | | | | |